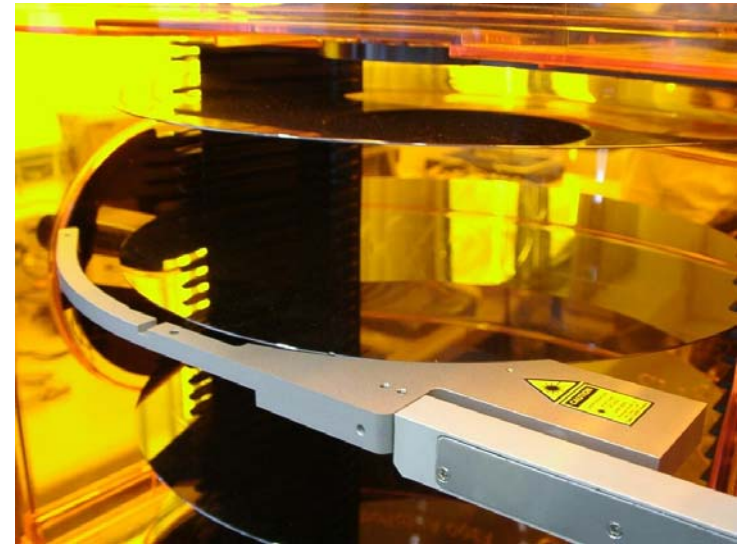


E220 / E500 Implanter: Thru Beam Mapper Upgrade (TBM)

Thru Beam Mapper Upgrade

The TBM upgrade is either a replacement of existing reflective mapper or a new option added on the Fixload 300mm loadport.



Value Proposition:

The Thru Beam Mapper upgrade is for customers who are looking to update from existing reflective mapping technology or to add wafer mapping capabilities for highly accurate repeatable detection of wafer presence and absence states



E220 / E500 Implanter: Thru Beam Mapper Upgrade (TBM)

Features

- Laser based through beam technology
- Detects cross and double slotted wafers
- Independent drive
- 8.5 second mapping time for 25 wafer FOUP
- Can replace reflective mapper (Fixmap)
- Report wafer thickness and location referencing horizontal datum plane

Benefits

- Reliable mapping (works for all wafer coatings)
- Field upgrade
- Easy to install
- Backwards compatible